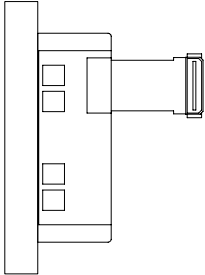


WIREBONDING CHECKLIST FOR CMS TOB HYBRIDS

Program: CMS-CH2 or CMS-CHI

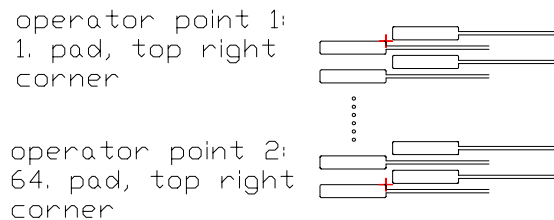
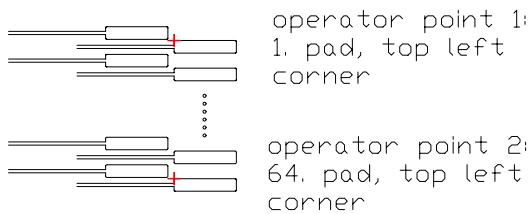
Part Orientation:



1. Pitch Adapter to Chip Bonds

Lead Reference System (L): Pitch Adapter

Die Reference System (U): Chip



First Bond: Pitch Adapter

Bond time: 20 ms

USG Current: 60 to 75mA

Force: 20

Second Bond: Chip

Bond time: 20 ms

USG Current: 48 to 55mA

Force: 35

Loop Parameters:

Shape: square

Loop height: short bonds 33 mils, long bonds 48 mils

Clear height: short bonds 53 mils, long bonds 68 mils

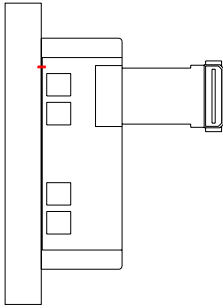
clamp close at loop

Tail Parameters:

Feed: 75

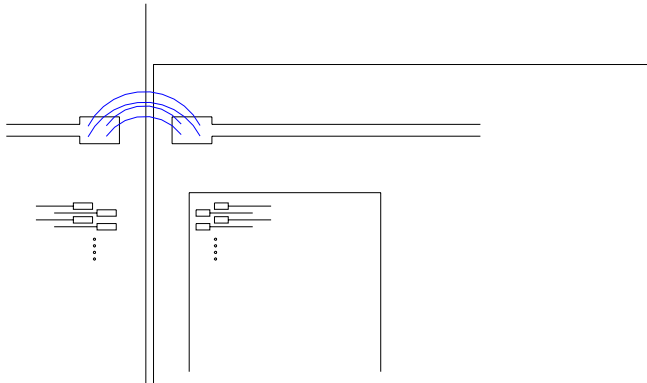
2. Hybrid Bias Bonds

Bias Bonds Location:



Pitch Adapter to Gold Pad on Hybrid:

Place 4 bonds, 2 short, 2 long



First Bond: Pitch Adapter

Bond time: 20ms

USG Current: 65 to 75mA

Force: 20

Loop Parameters:

Shape: square

Loop height: short bonds 60 mils, long bonds 70 mils

Clamp close at loop

Second Bond: Gold

Bond time: 30 to 35 ms

USG Current: 60 to 70mA

Force: 25

Tail Parameters:

Feed: 75